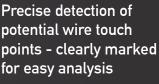
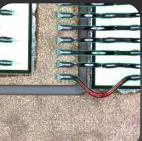
Wirebond inspection

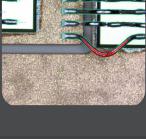
- STRATUS VISION
- © Effortlessly create applications with Al-driven technology
- O Comprehensive inspection of your electronics from wirebonds to chip and conductor
- Wirebond error detection uncovering all common issues
- Rapid wirebond inspection for large-scale electronics - 8x8" area inspected in just 30 seconds



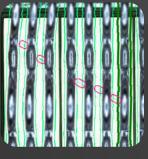


Thorough inspection of wire loops and flat wires - no detail goes unchecked

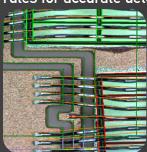




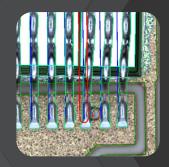
Streamlined inspection of DCB, chip and wirebond - all in one step



Dynamic component inspection - automatic shifting of rules for accurate detection



Solderpaste blobs that connect wirebonds are found



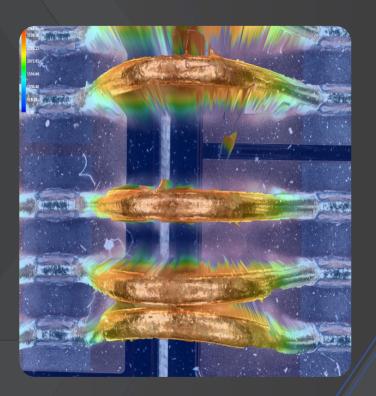
Contact us via E-Mail: sales@stratusvision.com



www.stratusvision.com

Unique advantages





Stratus Vision unique approach to inspection has transferred to the wirebond space to create one of the most comprehensive solutions available at this time. Our fast image acquisition technique enables image capture within seconds for large area substrates or substrates in carriers. We coupled this with our state of the art inspection approach that will help you solve your most complex inspection requirements with great success and ease. Setup is generally made with CAD data as input to ensure fast setup times as well as simple and fast transfer to other machines or product types. While we use CAD data as input, our solutions offer high flexibility in recognising standard production variance and shift. Stratus Visions approach derived from our background in flex substrate inspection, finds each component individually and identifies all defects and criteria based on the identified position rather than its designed position.

Stratus Visions inspection solution are constantly developed to be on the leading edge of technology and therefore we have integrated Al Defect classification deep in to the software core to help you reduce operator input and improve output. All of Stratus Visions systems while performing their inspection tasks are also fully blown metrology solutions that can measure and report on different critical dimensions as well as fail for tolerance on measurements. Our software is constantly under development and hardware independent so you can purchase almost any of our inspection solutions and get the full benefit of the software adapted for each unique hardware setup. OPC/UA and SECS/GEM integration is available as well as review and offline programming stations.

